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CY14V256LA-BA35XI Status: In Production

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CY14V256LA-BA35XI

Automotive Qualified	N
Min. Operating Voltage (V)	2.70
Max. Operating Voltage (V)	3.60
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	85
Frequency (MHz)	N/A
Temp. Classification	Industrial
Max. Operating VCCQ (V)	1.95
Min. Operating VCCQ (V)	1.65
Speed (ns)	35
Density (Kb)	256
Organization (X x Y)	32Kb x 8

Pricing & Inventory Availability

1-10 unit Price*	11-100 unit Price*	101-1000 unit Price*	1001 + unit Price*

Availability	Quantity	Ships In	Order Now

* Prices are shown in United States dollars and are for budgetary use only.

Packaging / Ordering

Package	FBGA
No. of Pins	48
Package Dimensions	393 L X 1.2 H X 236 W (Mils)
Package Weight	119.15 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TRAY
Package Carrier Drawing / Orientation	Drawing, Package Orientation
Standard Pack Quantity	299
Minimum Order Quantity (MOQ)	299
Order Increment	299
Estimated Lead Time (days)	56
HTS Code	8542.32.0040
ECCN	3A991

ECCN Suball	(B.2.A.)
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Quality and RoHS	
Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Sn/Ag/Cu
Marking	Cypress Marking Format
Package Material Declaration 48 - BGA (6X10X1.2MM) PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET Last Update: 07/09/2012	
IPC 1752 Material Declaration IPC-1752-2_V1.1_BGA 48 (6 X 8 MM) _ASET_SNAGCU(SAC405) Last Update: 07/04/2012	
RoHS Analysis Certificates (CoA) PACKAGE ROHS ANALYSIS REPORT - BGA (BK/BP 36, 42, 48, 96) (BW 96,100,119,144,165,172,196,209,256,400) USING MOLD COMPOUND KEG2270, ADHESIVE 2025D, SAC405 - ASE TAIWAN ASSEMBLY Last Update: 07/04/2012	
RoHS Analysis Certificates (CoA) for Direct Materials Please click here	
Device Qualification Reports  FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. Please click here .	

Technical Documents
Application Notes (11) AN43593 - Storage Capacitor (V_{CAP}) Options for Cypress nvSRAM Last Update: 21/03/2013 AN55663 - Migrating from CY14E256L/STK14C88 to CY14E256LA Last Update: 18/03/2013 AN6068 - Replacing 4Mbit (256K x16) MRAM with Cypress nvSRAM Last Update: 13/03/2013 AN43380 - HSR Operation in nvSRAMs Last Update: 03/10/2012 Show More
Product Information Notice (PIN) (1) PIN135200 Last Update: 21/03/2013

Support and Community
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